

## HSC276

### Silicon Schottky Barrier Diode for Detector and Mixer

REJ03G0134-0200Z  
(Previous: ADE-208-421A)  
Rev.2.00  
Nov.10.2003

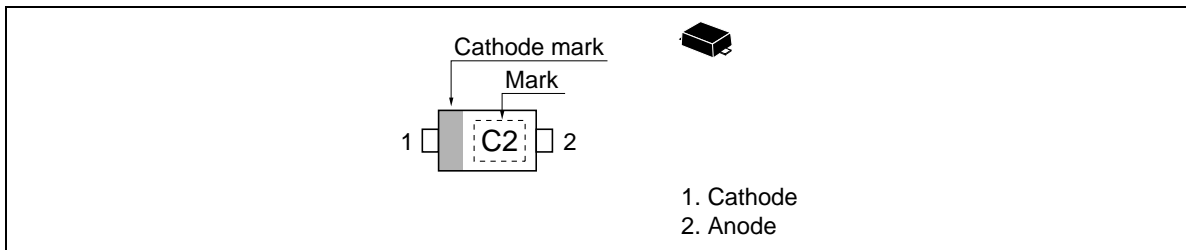
#### Features

- High forward current, Low capacitance.
- Ultra small Flat Package (UFP) is suitable for surface mount design.

#### Ordering Information

Type No.	Laser Mark	Package Code
HSC276	C2	UFP

#### Pin Arrangement



**Absolute Maximum Ratings**

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	3	V
Average rectified current	I <sub>O</sub>	30	mA
Junction temperature	T <sub>j</sub>	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

**Electrical Characteristics**

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse voltage	V <sub>R</sub>	3	—	—	V	I <sub>R</sub> = 1 mA
Reverse current	I <sub>R</sub>	—	—	50	μA	V <sub>R</sub> = 0.5 V
Forward current	I <sub>F</sub>	35	—	—	mA	V <sub>F</sub> = 0.5 V
Capacitance	C	—	—	0.85	pF	V <sub>R</sub> = 0.5 V, f = 1 MHz
ESD-Capability <sup>*1</sup>	—	30	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

Note: 1. Failure criterion ; I<sub>R</sub> ≥ 100 μA at V<sub>R</sub> = 0.5 V

Main Characteristics

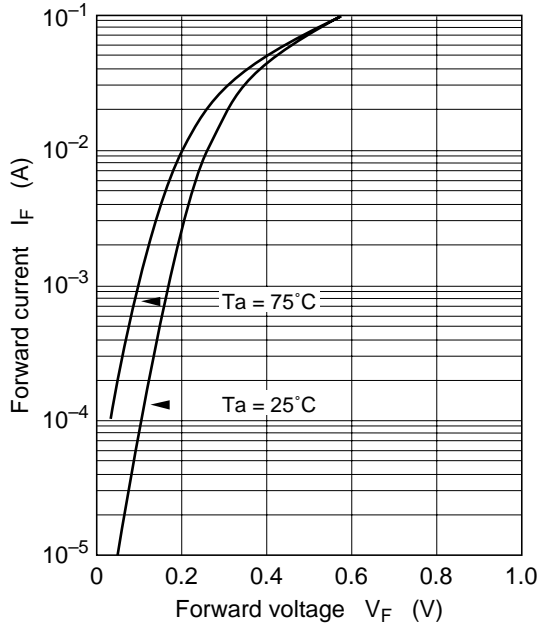


Fig.1 Forward current vs. Forward voltage

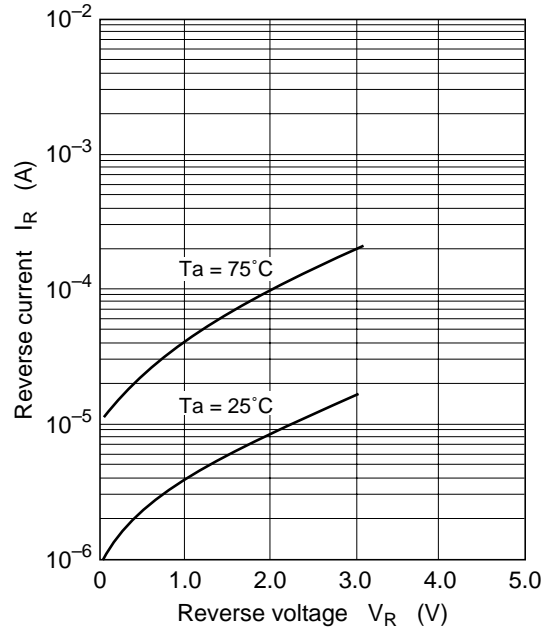


Fig.2 Reverse current vs. Reverse voltage

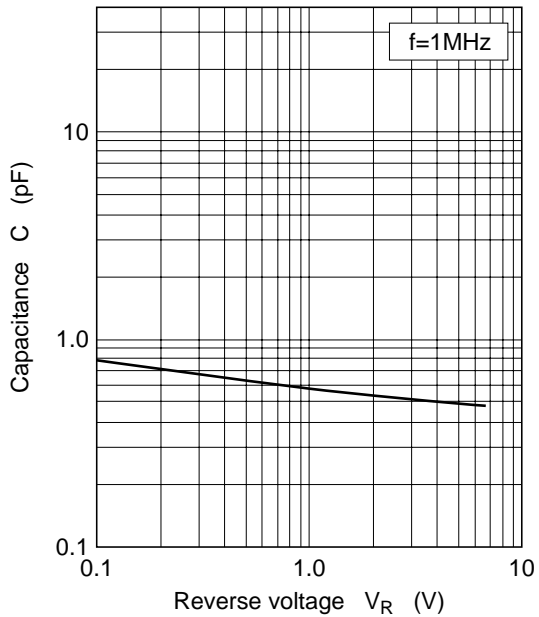
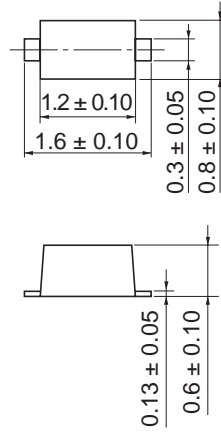


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

As of January, 2003  
Unit: mm



Package Code	UFP
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.0016 g

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